

2017 IEEE S3S Conference

16 – 19 October 2017, Hyatt Regency San Francisco Airport

s3sconference.org

IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference

Overview This industry-wide event has gathered, for over 40 years, industry leaders and widely known experts, in a social-oriented environment. Our contributed papers and invited talks are focused on SOI Technology, Low-Voltage Devices/Circuits/Architectures, and 3D Integration. These 3 technologies will play a major role in tomorrow's industry as they enable application-tailored and Energy / Cost efficient circuit designs.

Important Dates

Paper Submission Deadline: May 22, 2017

Acceptance Notification: July 1, 2017

The conference at a glance

Monday to Wednesday: Technical Sessions

Thursday, October 19: **Fully-Depleted SOI Circuit Design** full-day Tutorial

Tuesday, October 17: **Monolithic 3D** half-day Tutorial

Scope We welcome papers in the following areas:

Silicon On Insulator (SOI)

- Advanced Materials, Substrate and Processes
- Device Physics, Characterization and Modeling
- Device/Circuit Integration
- SOI Design, Circuits and Applications

- Non-Digital Devices and Applications (RF, High-Voltage, Photonics, NEMS, MEMS, Analog...)
- New SOI Structures, Circuits and Applications

Low-Voltage Microelectronics

- Space-Based and Unattended Remote Sensors
- Biomedical Devices
- Low-Voltage Handheld/wireless systems
- Ultra-Low-Power Digital Computation
- Analog and RF Technologies

- Low Voltage Memory Technologies
- Energy Harvesting Techniques
- Asynchronous Circuits
- Novel Device and Fabrication Technology

3D Integration

- Low Thermal Budget Processing
- Fabrication Techniques and Bonding Methods
- Design and Test Methodologies
- Processes for Multi Wafer Stacking
- 3D IC EDA and Design Technology

- Heterogeneous Structures
- 3D Manufacturing and Logistics
- Reliability of 3D Circuits
- Fault Tolerant 3D Designs

Paper Submission

Prospective authors should prepare a 2-page abstract (guidelines at s3sconference.org/preparation-of-abstracts/).

Acceptance is based on paper's technical quality and relevance.

Conference manager contact

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